

ABSTRACT

A collet according to the present disclosure is used for compressing an adhesive-attached chip obtained through a step of singulating a wafer, and includes a main body having a first pressing surface to which a pressing force from a compressing device is directly transmitted, and a projecting portion having a second pressing surface provided along an outer circumference of the first pressing surface, the first pressing surface and the second pressing surface forming a holding surface for holding the adhesive-attached chip.

Fig. 1